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/TITLE: MODULAR LUG BLOCK ASSEMBLY ATTORNEY DOCKET NO.: 003B.0024.U1(US)

Assistant Commissioner for Patents Washington, D.C. 20231

Information Disclosure Statement

(37 C.F.R. §1.97(c))

Sir:

The following information is being disclosed to the U.S. Patent and Trademark Office as information that may be material to the examination of the above-identified patent application.

Applicant's Attorney is aware of the following art:

U.S. Patent No. 6,497,592 B1

Copies of the art are enclosed with a Form PTO-1449 for the Examiner's use.

Each item of information contained in this Information Disclosure Statement was cited in a communication from a

foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Statement, or

No item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the statement after making reasonable inquiry, no item of information contained in this Statement was known to any individual designated in 37 C.F.R. §1.56(c) more than three months prior to the filing of this Statement.

The filing of this Statement is not to be construed as a representation that a search has been made regarding the claimed invention (37 C.F.R. $\S1.97(g)$) or that no other possible material information exists. In addition, the filing of this Statement is not to be construed to be an admission that the information cited in the Statement is, or is considered to be, material to patentability (37 C.F.R. $\S1.97(h)$).

Respectfully submitted,

1/1, /03

Mark F. Harrington (Req. No. 31,686)

Date

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail on the date shown below in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

1/22/2003